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FGH80N60FD

600 V Field Stop IGBT

Features

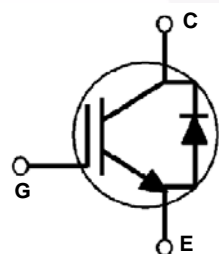
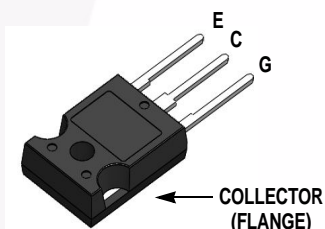
- High Current Capability
- Low Saturation Voltage: $V_{CE(sat)} = 1.8\text{ V @ } I_C = 40\text{ A}$
- High Input Impedance
- Fast Switching
- RoHS Compliant

Applications

- Induction Heating, PFC, Telecom, ESS

General Description

Using novel field stop IGBT technology, Fairchild's field stop IGBTs offer the optimum performance for induction heating, telecom, ESS and PFC applications where low conduction and switching losses are essential.



Absolute Maximum Ratings

Symbol	Description	Ratings	Unit
V_{CES}	Collector-Emitter Voltage	600	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C = 25^\circ\text{C}$	80	A
	Collector Current @ $T_C = 100^\circ\text{C}$	40	A
I_{CM} (1)	Pulsed Collector Current @ $T_C = 25^\circ\text{C}$	160	A
P_D	Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$	290	W
	Maximum Power Dissipation @ $T_C = 100^\circ\text{C}$	116	W
T_J	Operating Junction Temperature	-55 to +150	$^\circ\text{C}$
T_{stg}	Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Notes :

(1) Repetitive rating : Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$ (IGBT)	Thermal Resistance, Junction-to-Case	--	0.43	$^\circ\text{C/W}$
$R_{\theta JC}$ (Diode)	Thermal Resistance, Junction-to-Case	--	1.5	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	40	$^\circ\text{C/W}$

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGH80N60FDTU	FGH80N60FD	TO-247	Tube	N/A	N/A	30

Electrical Characteristics of the IGBT T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
BV _{CES}	Collector-Emitter Breakdown Voltage	V _{GE} = 0 V, I _C = 250 μA	600	--	--	V
ΔBV _{CES} / ΔT _J	Temperature Coefficient of Breakdown Voltage	V _{GE} = 0 V, I _C = 250 μA	--	0.6	--	V/°C
I _{CES}	Collector Cut-Off Current	V _{CE} = V _{CES} , V _{GE} = 0 V	--	--	250	μA
I _{GES}	G-E Leakage Current	V _{GE} = V _{GES} , V _{CE} = 0 V	--	--	±400	nA
On Characteristics						
V _{GE(th)}	G-E Threshold Voltage	I _C = 250 μA, V _{CE} = V _{GE}	4.5	5.5	7.0	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I _C = 40 A, V _{GE} = 15 V	--	1.8	2.4	V
		I _C = 40 A, V _{GE} = 15 V, T _C = 125°C	--	2.05	--	V
Dynamic Characteristics						
C _{ies}	Input Capacitance	V _{CE} = 30 V, V _{GE} = 0 V, f = 1 MHz	--	2110	--	pF
C _{oes}	Output Capacitance		--	200	--	pF
C _{res}	Reverse Transfer Capacitance		--	60	--	pF
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{CC} = 400 V, I _C = 40 A, R _G = 10 Ω, V _{GE} = 15 V, Inductive Load, T _C = 25°C	--	21	--	ns
t _r	Rise Time		--	56	--	ns
t _{d(off)}	Turn-Off Delay Time		--	126	--	ns
t _f	Fall Time		--	50	100	ns
E _{on}	Turn-On Switching Loss		--	1	1.5	mJ
E _{off}	Turn-Off Switching Loss		--	0.52	0.78	mJ
E _{ts}	Total Switching Loss	--	1.52	2.28	mJ	
t _{d(on)}	Turn-On Delay Time	V _{CC} = 400 V, I _C = 40 A, R _G = 10 Ω, V _{GE} = 15 V, Inductive Load, T _C = 125°C	--	20	--	ns
t _r	Rise Time		--	54	--	ns
t _{d(off)}	Turn-Off Delay Time		--	131	--	ns
t _f	Fall Time		--	70	--	ns
E _{on}	Turn-On Switching Loss		--	1.1	--	mJ
E _{off}	Turn-Off Switching Loss		--	0.78	--	mJ
E _{ts}	Total Switching Loss	--	1.88	--	mJ	
Q _g	Total Gate Charge	V _{CE} = 400 V, I _C = 40 A, V _{GE} = 15 V	--	120	--	nC
Q _{ge}	Gate-Emitter Charge		--	14	--	nC
Q _{gc}	Gate-Collector Charge		--	58	--	nC

Electrical Characteristics of the Diode T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max	Unit	
V _{FM}	Diode Forward Voltage	I _F = 20 A	T _C = 25°C	-	2.3	2.8	V
			T _C = 125°C	-	1.7	-	
t _{rr}	Diode Reverse Recovery Time	I _F = 20 A, di _F / dt = 200 A/μs	T _C = 25°C	-	36	-	ns
			T _C = 125°C	-	105	-	
I _{rr}	Diode Reverse Recovery Current	I _F = 20 A, di _F / dt = 200 A/μs	T _C = 25°C	-	2.6	-	A
			T _C = 125°C	-	7.8	-	
Q _{rr}	Diode Reverse Recovery Charge	I _F = 20 A, di _F / dt = 200 A/μs	T _C = 25°C	-	46.8	-	nC
			T _C = 125°C	-	409	-	



Typical Performance Characteristics

Figure 1. Typical Output Characteristics

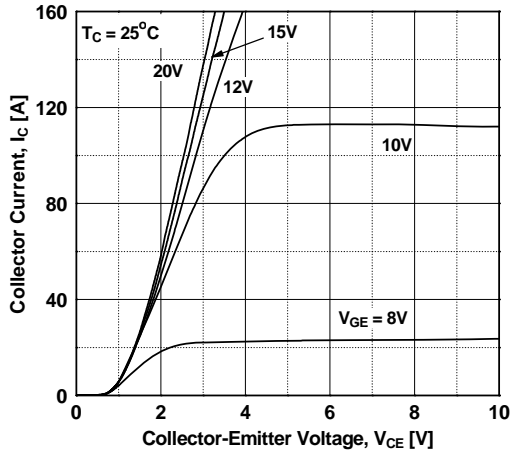


Figure 2. Typical Saturation Voltage Characteristics

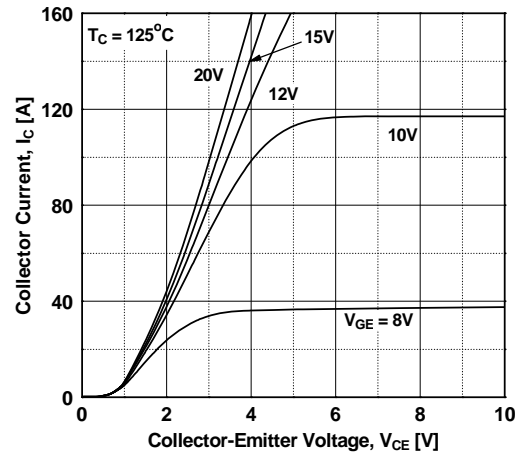


Figure 3. Typical Saturation Voltage Characteristics

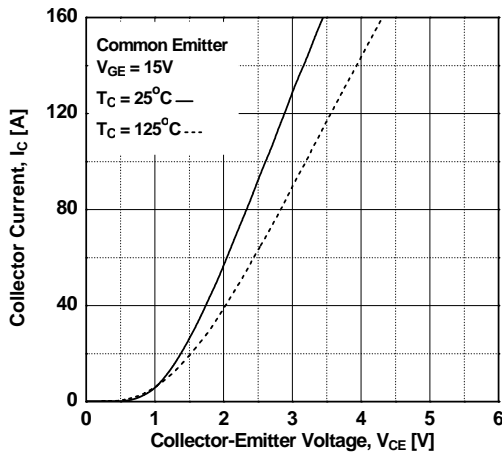


Figure 4. Transfer Characteristics

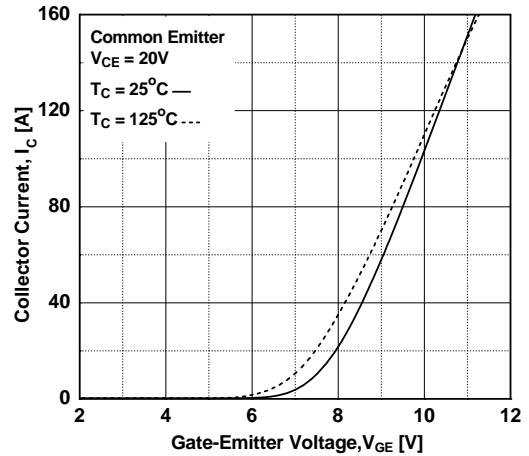


Figure 5. Saturation Voltage vs. Case

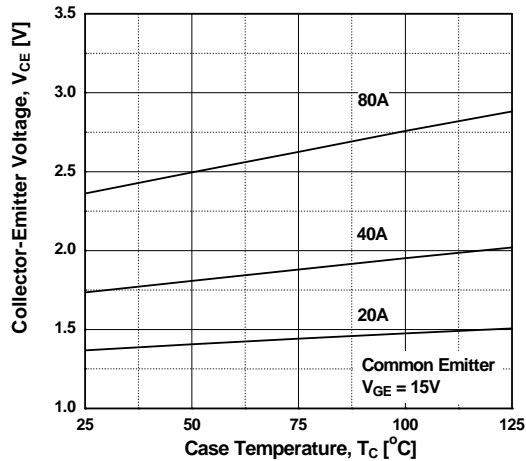
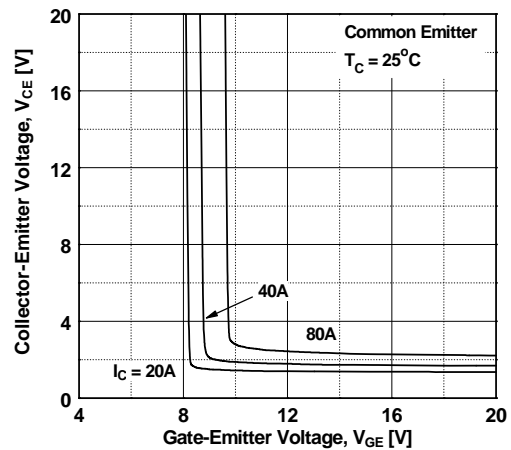


Figure 6. Saturation Voltage vs. Vge



Typical Performance Characteristics (Continued)

Figure 7. Saturation Voltage vs. V_{GE}

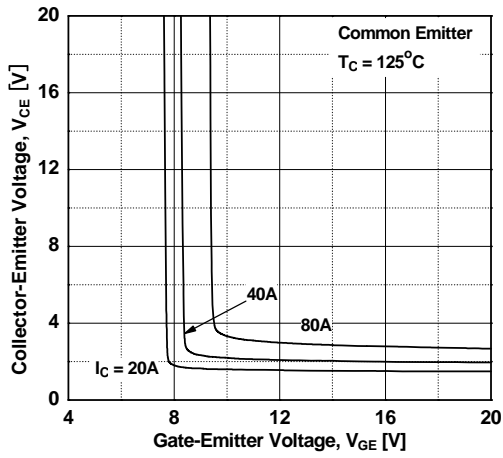


Figure 8. Capacitance Characteristics

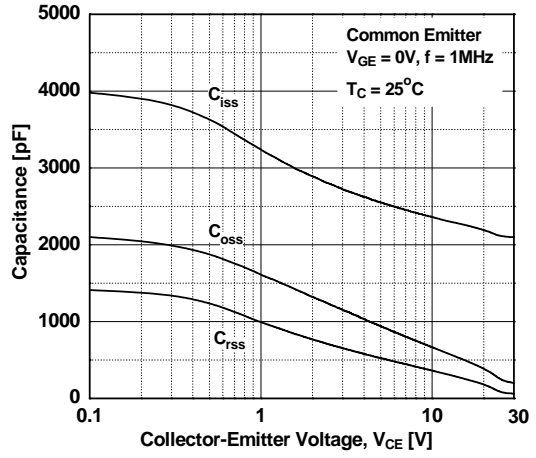


Figure 9. Gate Charge Characteristics

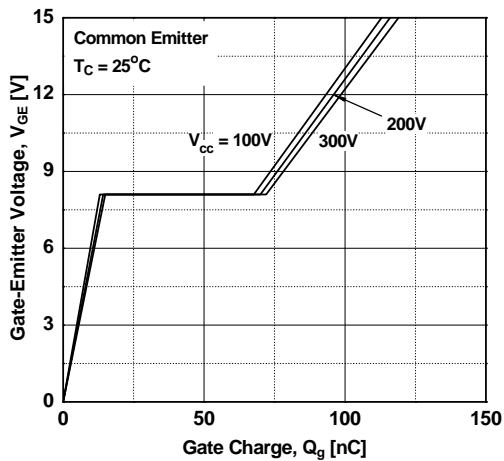


Figure 10. SOA Characteristics

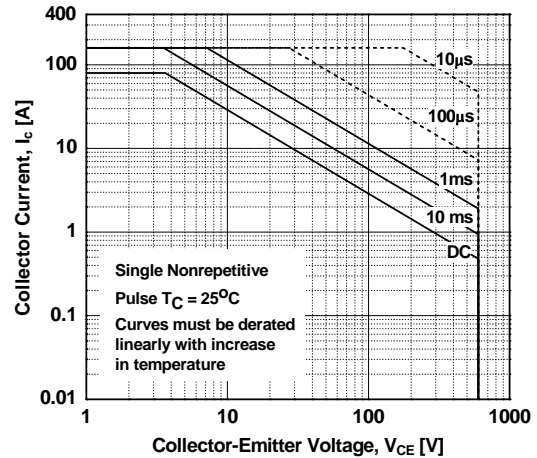


Figure 11. Turn-Off Switching SOA Characteristics

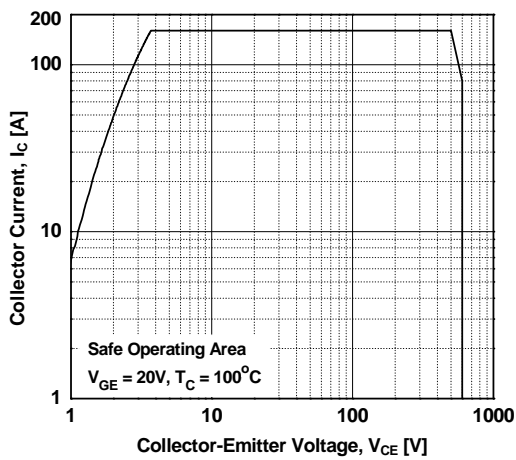
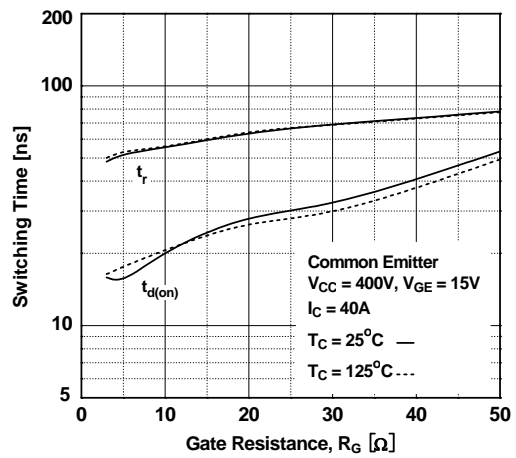


Figure 12. Turn-On Characteristics vs. Gate Resistance



Typical Performance Characteristics (Continued)

Figure 13. Turn-Off Characteristics vs. Gate Resistance

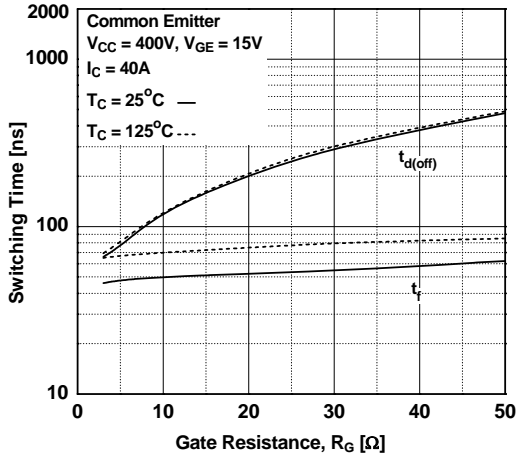


Figure 14. Turn-On Characteristics vs. Collector Current

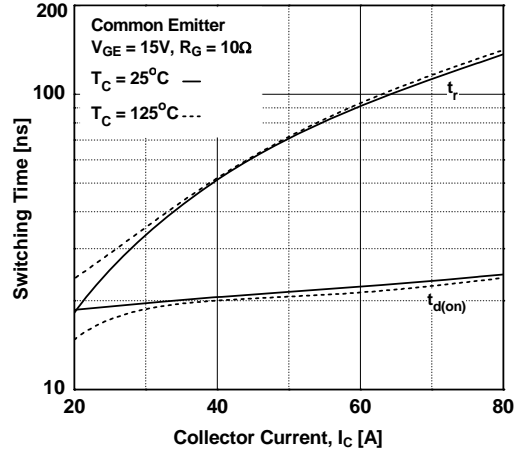


Figure 15. Turn-Off Characteristics vs. Collector Current

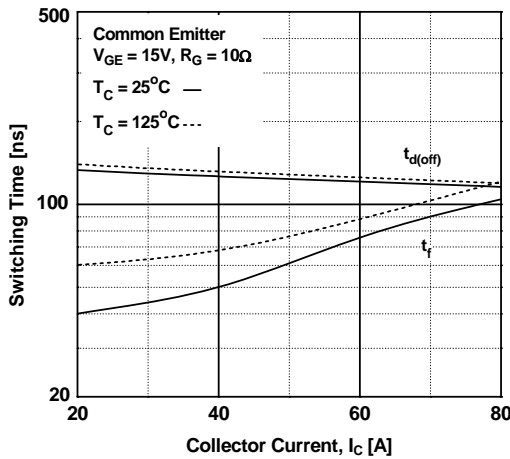


Figure 16. Switching Loss vs Gate Resistance

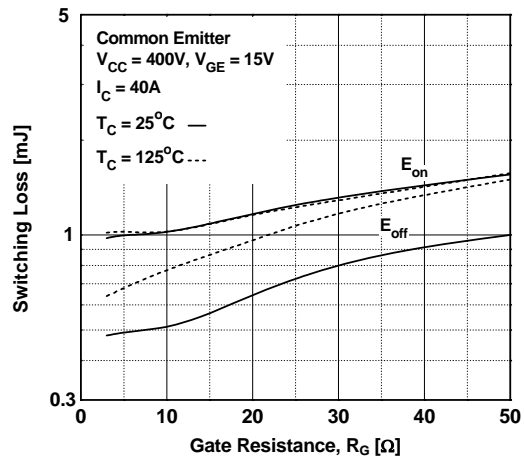
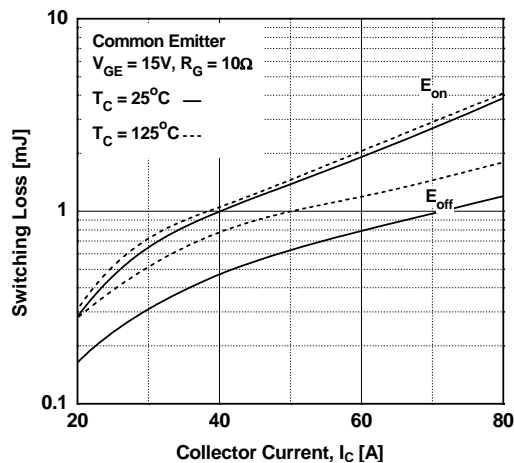


Figure 17. Switching Loss vs Collector Current



Typical Performance Characteristics (Continued)

Figure 18. Transient Thermal Impedance of IGBT

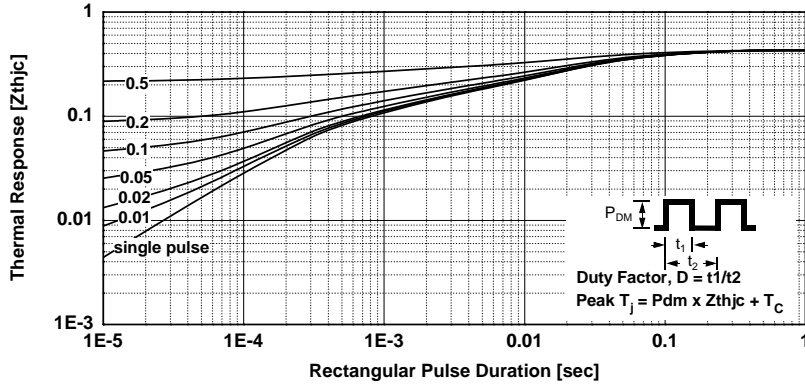


Figure 19. Forward Characteristics

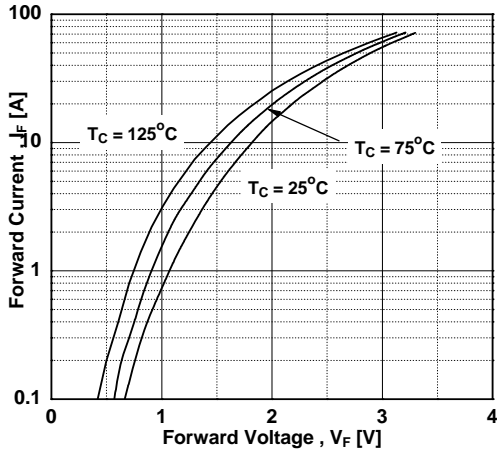


Figure 20. Stored Charge

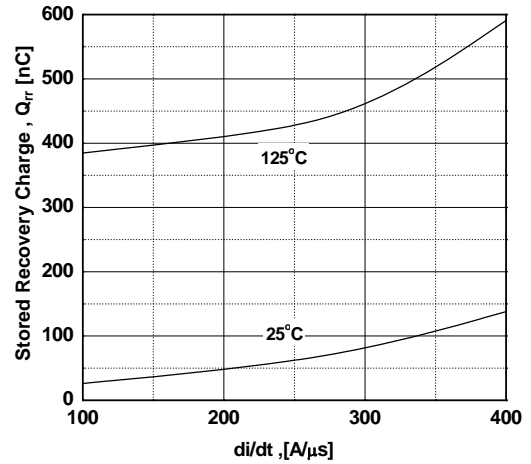


Figure 21. Reverse Recovery Time

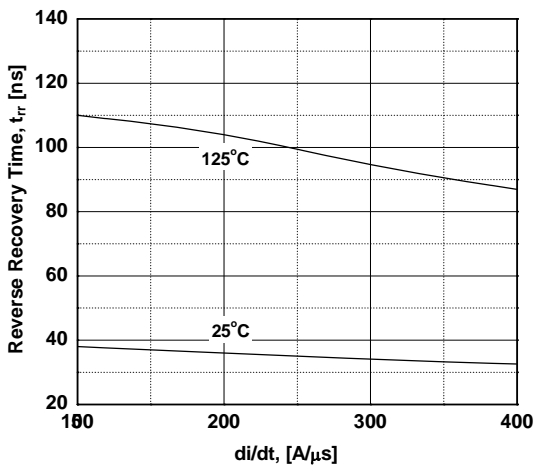
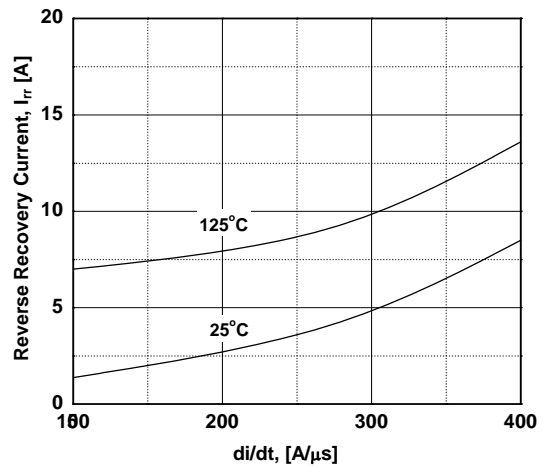
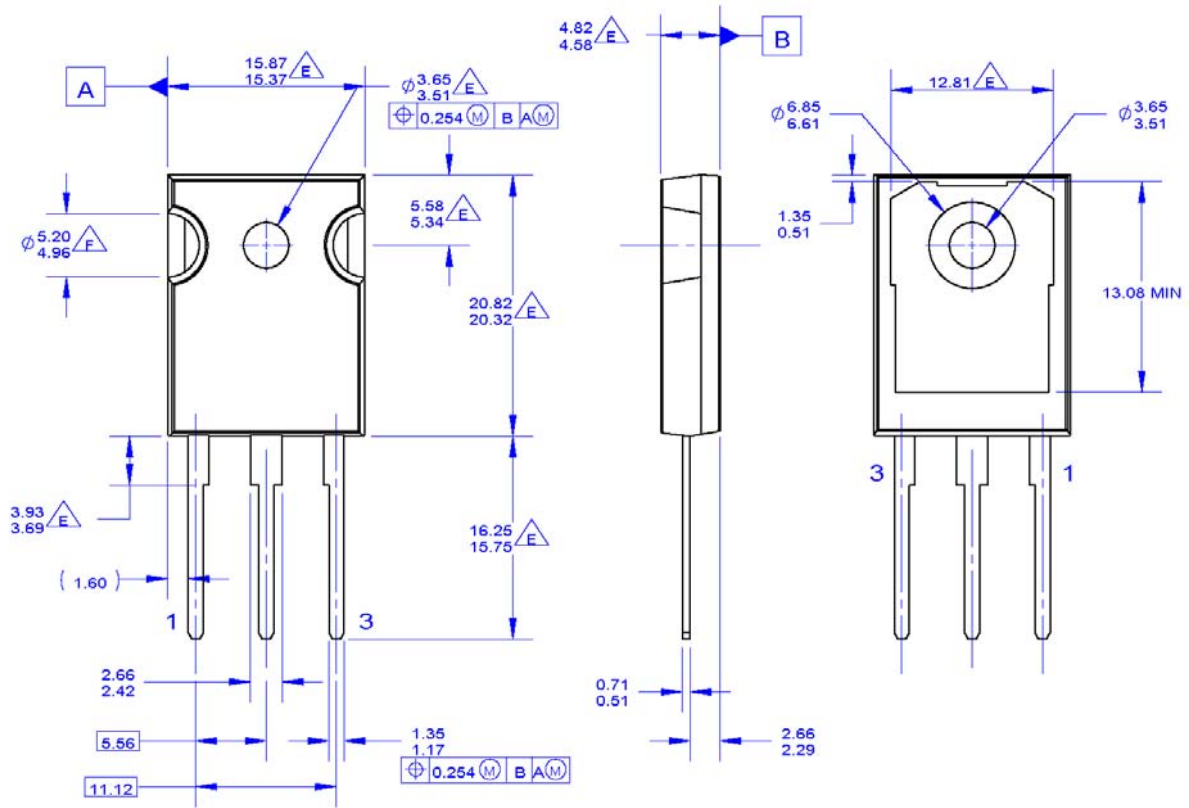


Figure 22. Reverse Recovery Current



Mechanical Dimensions



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- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DRAWING CONFORMS TO ASME Y14.5 - 1994

- DOES NOT COMPLY JEDEC STANDARD VALUE
- NOTCH MAY BE SQUARE
- G. DRAWING FILENAME: MKT-TO247A03_REV03

Figure 23. TO-247 3L - TO-247,MOLDED,3 LEAD,JEDEC VARIATION AB

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